

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): Ultrahigh purity copper having a residual resistance ratio of ~~38,000 or greater~~ 40,000 to 100,000 and a purity of 8N or higher, gas components of O, C, N, H, S and P being excluded from a determination of said purity, and a content of impurities in said ultrahigh purity copper excluding said gas components totaling no more than 0.01ppm.

Claim 2 (original): The ultrahigh purity copper according to claim 1, wherein the respective elements of O, C, N, H, S and P as gas components are 1ppm or less.

Claims 3-6 (canceled).

Claim 7 (previously presented): An ultrahigh purity copper according to claim 1, prepared by a process comprising the steps of, upon subjecting copper to high purification with an electrolytic method, partitioning an electrolytic bath with an anion exchange membrane into an anode side and a cathode side of the electrolytic bath, intermittently or continuously extracting an anolyte from the anode side of said electrolytic bath, adding active carbon into the extracted anolyte and agitating the extracted anolyte to absorb impurities to the active carbon, removing the absorbed impurities together with the active carbon from the extracted anolyte by filtration to obtain a high purity copper electrolytic solution, and intermittently or continuously

pouring the high purity copper electrolytic solution into the cathode side of the electrolytic bath, and electrolyzing the high purity copper electrolytic solution.

Claim 8 (previously presented): An ultrahigh purity copper according to claim 7, wherein the respective elements of O, C, N, H, S and P as gas components are 1ppm or less.

Claim 9 (currently amended): An ultrahigh purity copper according to claim 2, wherein the content of silver (Ag) in said ultrahigh purity copper is less than 0.005ppm, wherein the content of aluminum (Al) in said ultrahigh purity copper is less than 0.001ppm, and said the content of iron (Fe) in said ultrahigh purity copper is less than 0.001ppm.

Claim 10 (currently amended): An ultrahigh purity copper according to claim 1, wherein the content of silver (Ag) in said ultrahigh purity copper is less than 0.005ppm, wherein the content of aluminum (Al) in said ultrahigh purity copper is less than 0.001ppm, and said the content of iron (Fe) in said ultrahigh purity copper is less than 0.001ppm.

Claim 11 (canceled).

Claim 12 (currently amended): An ultrahigh purity copper according to claim [11] 9, wherein the purity of the ultrahigh purity copper is higher than 8N.

Claim 13 (canceled).

Claim 14 (currently amended): An ultrahigh purity copper according to claim [11] 9, wherein a content of sulfur (S) in the ultrahigh purity copper is less than 0.005ppm.

Claim 15 (previously presented): A copper sputtering target having superior deposition characteristics made from the ultrahigh purity copper according to claim 14.